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| <b>Title of Change:</b>                          | PCN Update Notice - Cancellation of IPCN20730.   |  |  |
| <b>Proposed first ship date:</b>                 | 18 October 2016  |  |  |
| <b>Contact information:</b>                      | Contact your local ON Semiconductor Sales Office   |  |  |
| <b>Samples:</b>                                  | Contact your local ON Semiconductor Sales Office   |  |  |
| <b>Additional Reliability Data:</b>              | Contact your local ON Semiconductor Sales Office   |  |  |
| <b>Type of notification:</b>                     | ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.   |  |  |
| <b>Change category:</b>                          | <input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>IPCN Cancellation</u>   |  |  |
| <b>Change Sub-Category(s):</b>                   | <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change<br><input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking<br><input checked="" type="checkbox"/> Other: IPCN Cancellation_____  |  |  |
| <b>Sites Affected:</b>                           | <input type="checkbox"/> All site(s) <input checked="" type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s)   |  |  |
| <b>Description and Purpose:</b>                  | <p>This Update Notice announces to customers the Cancellation of IPCN20730 due to cancellation of back grind &amp; back metal capacity expansion at the CZ4 Wafer Fab project at Roznov, Czech Republic.</p> <p><b>IPCN20730</b> – was previously announced the back grind &amp; back metal capacity expansion at the CZ4 Wafer Fab at Roznov, Czech Republic. This expansion will supplement the current back grind &amp; back capability ISMF Fab in Seremban, Malaysia.</p> |  |  |
| <b>List of Affected Standard Parts:</b>          | NGB15N41AACL4G<br>NGB18N40ACLB4G<br>NGB8202ANT4G<br>NGB8204ANT4G<br>NGB8206ANSL3G<br>NGB8206ANT4G<br>NGB8206ANTF4G<br>NGB8207ABNT4G<br>NGB8207BNT4G<br>NGB8245NT4G<br>NGD15N41AACL4G<br>NGD18N40ACLB4G<br>NGD18N45CLB4G<br>NGD8201ANT4G<br>NGD8201BNT4G<br>NGD8205ANT4G<br>NGD8209NT4G   |  |  |
| <b>List of Affected Customer Specific Parts:</b> | <p><i>NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN &amp; CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.</i></p>   |  |  |